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Donald C. O’Shea  received a Bachelor of Physics from the University of Akron, a Master of Science in Physics from Ohio State University, and a Ph.D. in Physics from Johns Hopkins University. Following his work at Hopkins, he was a postdoctoral fellow at the Gordon McKay Laboratory at Harvard University. In 1970, he joined the faculty of the School of Physics at Georgia Institute of Technology, where he is now Professor of Physics. He has been a Visiting Scholar at the Optical Sciences Center of the University of Arizona and at the University of Oulu, Finland.

Dr. O’Shea has co-authored an undergraduate textbook, *An Introduction to Lasers and Their Applications*, and authored an undergraduate textbook, *Elements of Modern Optical Design*. He created the Optics Discovery Kit for the Optical Society of America for use in precollege education. He was awarded the Esther Hoffman Beller Award by the Optical Society of America for “excellence in the field of optics education.” He is the co-inventor of a display system for low-vision patients and has published more than 50 scientific publications and presented a similar number at national and international scientific meetings. Dr. O’Shea is a Fellow of the SPIE and the Optical Society of America. He was SPIE President during 2000. He is currently the editor of *Optical Engineering*, SPIE’s flagship journal.

Thomas J. Suleski has been actively involved in research and development of optical microsystems and microfabrication techniques for over eleven years at places such as the Georgia Institute of Technology and Digital Optics Corporation. Dr. Suleski has multiple patents and numerous technical publications on the design, fabrication, and testing of micro-optical components and systems, covering topics that include rapid, low-cost fabrication techniques for micro-optics, near-field diffraction properties of periodic structures, diffractive optic design, grayscale microlithography, near-field holography, micoreplication, and integration of optical microsystems. He has been an invited speaker at several micro-optics conferences. Dr. Suleski has served as Associate Editor (Microfabrication) for the *Journal of Microlithography, Microfabrication, and Microsystems*, and has chaired multiple conferences on micro-optics technology. He is also an instructor for short courses on microfabrication technologies for micro-optics.

Alan Kathman has pursued a fascination with optics since high school. He earned a Bachelor's Degree in Physics at Purdue University and a Master's Degree in Physics at the University of Alabama at Huntsville. From 1985 to 1995, Mr. Kathman was employed by Teledyne Brown Engineering, where, in 1994, he was named “Scientist of the Year”. He is currently with Digital Optics Corporation and lives in Charlotte, North Carolina.

Mr. Kathman has authored or co-authored over 40 technical papers. He is an inventor with over 30 US patents and several foreign patents. Alan has designed and developed optical products for a number of applications. His professional interests include diffractive optics, micro-optics, interferometry and coherence, as well as lean development and product management. Mr. Kathman also enjoys explaining optical phenomena to his very tolerant wife and sons: Lesli, Brandon and Matthew.
Dennis W. Prather received the B.S.E.E., M.S.E.E., and Ph.D. from the University of Maryland in 1989, 1993, and 1997, respectively. During this time he worked as a senior research engineer for the Army Research Laboratory in the Optics Branch, where his efforts included work on the modeling, design, and fabrication of diffractive optical elements in both the scalar and vector regime, and their integration with active opto-electronic devices such as infrared focal plane arrays and VCSELs and began to develop the application of numerical electromagnetic models to the analysis of aperiodic-subwavelength and nanoscale-photonic devices. In 1997 he joined the faculty at the University of Delaware, where he is currently an Associate Professor in the Department of Electrical and Computer Engineering. There, he leads the Laboratory for Nano- and Integrated-Photonic Systems where the focus is on both the theoretical and experimental aspects of active and passive nanophotonic elements and their integration into optoelectronic subsystems.